

## DZ2702400L

### Silicon epitaxial planar type

For constant voltage / For surge absorption circuit  
DZ2S024 in SSSMini2 package

#### ■ Features

- Excellent rising characteristics of zener current  $I_Z$
- Low zener operating resistance  $R_Z$
- Halogen-free / RoHS compliant  
(EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

#### ■ Marking Symbol: 1J

#### ■ Packaging

Embossed type (Thermo-compression sealing) 10 000 pcs / reel (standard)

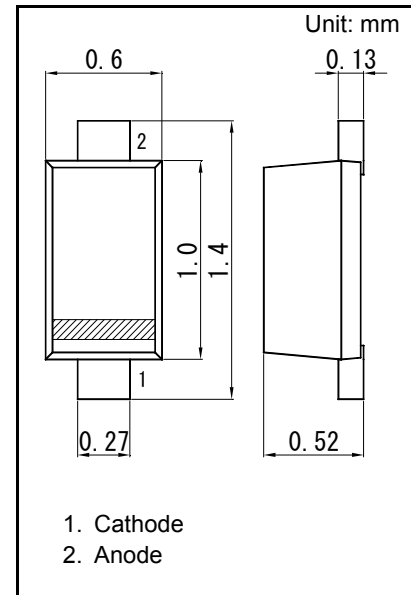
#### ■ Absolute Maximum Ratings $T_a = 25\text{ }^\circ\text{C}$

| Parameter                             | Symbol | Rating      | Unit |
|---------------------------------------|--------|-------------|------|
| Repetitive peak forward current       | IFRM   | 200         | mA   |
| Total power dissipation <sup>*1</sup> | PT     | 120         | mW   |
| Electrostatic discharge <sup>*2</sup> | ESD    | ±15         | kV   |
| Junction temperature                  | Tj     | 150         | °C   |
| Operating ambient temperature         | Topr   | -40 to +85  | °C   |
| Storage temperature                   | Tstg   | -55 to +150 | °C   |

Note) \*1: Mounted on glass epoxy print board. ( 45 mm x 45 mm x 1 mm)

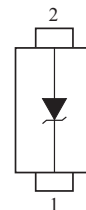
Solder in ( 0.4 mm x 0.3 mm)

\*2: Test method: IEC61000\_4\_2(C = 150 pF, R = 330 Ω, Contact discharge: 10 times)



|           |               |
|-----------|---------------|
| Panasonic | SSSMini2-F4-B |
| JEITA     | SC-104A       |
| Code      | SOD-723       |

#### Internal Connection



#### ■ Electrical Characteristics $T_a = 25\text{ }^\circ\text{C} \pm 3\text{ }^\circ\text{C}$

| Parameter                                              | Symbol | Conditions | Min  | Typ  | Max  | Unit  |
|--------------------------------------------------------|--------|------------|------|------|------|-------|
| Forward voltage                                        | VF     | IF = 10 mA |      |      | 1.0  | V     |
| Zener voltage <sup>*1, *2</sup>                        | VZ     | IZ = 5 mA  | 2.28 |      | 2.52 | V     |
| Zener operating resistance                             | RZ     | IZ = 5 mA  |      |      | 100  | Ω     |
| Reverse current                                        | IR     | VR = 1.0 V |      |      | 120  | μA    |
| Temperature coefficient of zener voltage <sup>*3</sup> | SZ     | IZ = 5 mA  |      | -1.7 |      | mV/°C |

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

2. Absolute frequency of input and output is 5 MHz.

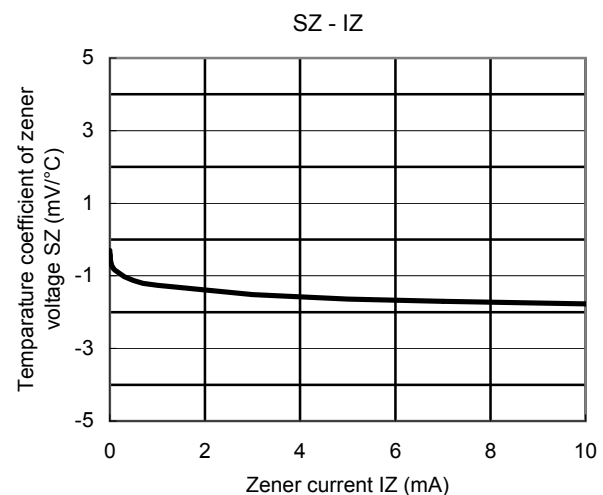
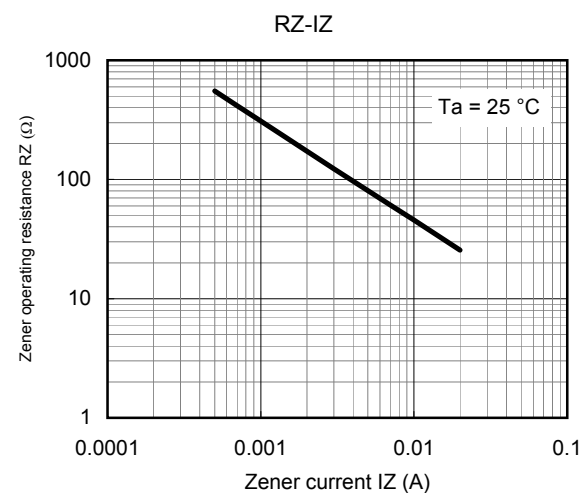
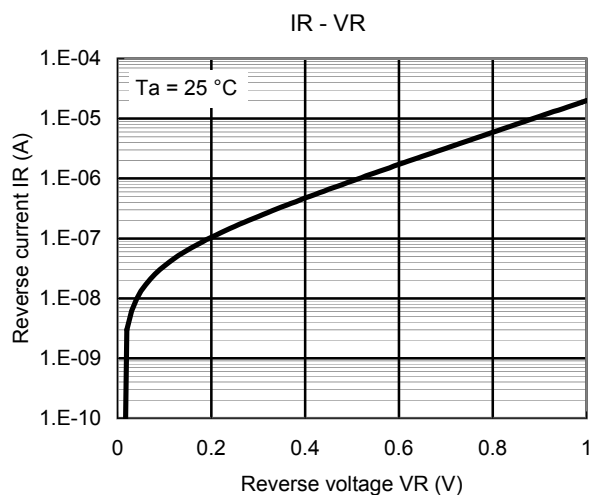
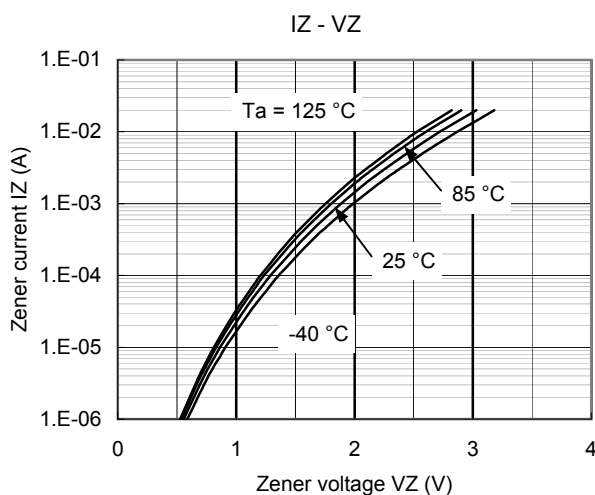
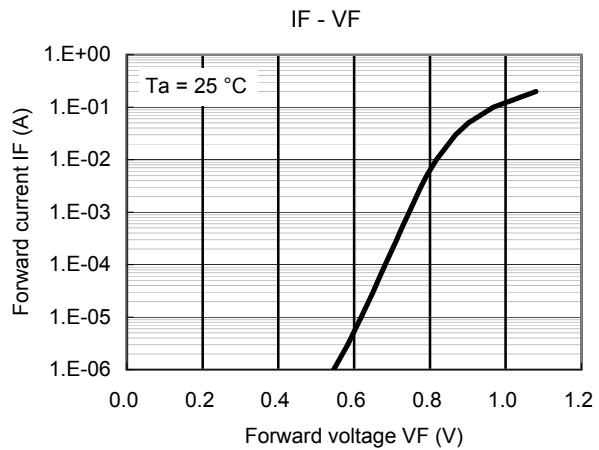
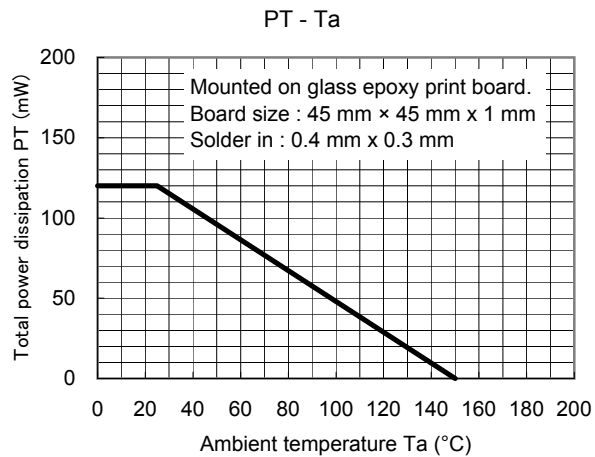
3. \*1 The temperature must be controlled 25 °C for VZ measurement.

VZ value measured at other temperature must be adjusted to VZ (25 °C)

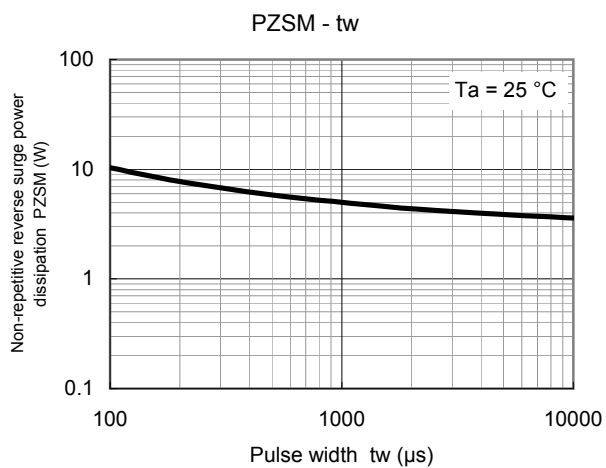
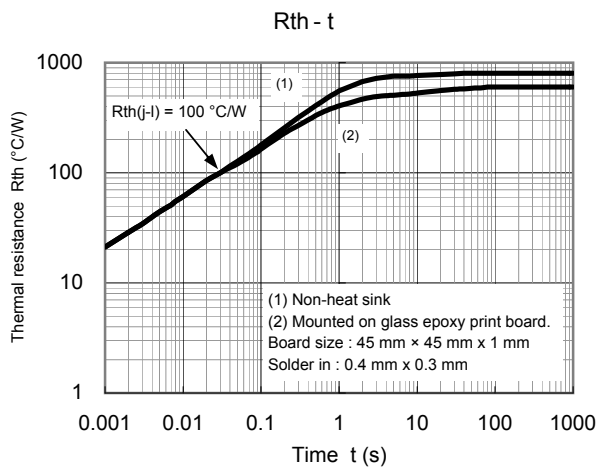
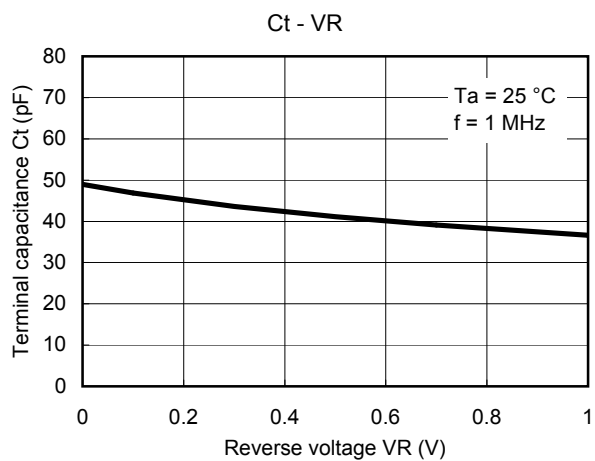
\*2 VZ guaranteed 20 ms after current flow.

\*3 Tj = 25 °C to 150 °C

Technical Data ( reference )

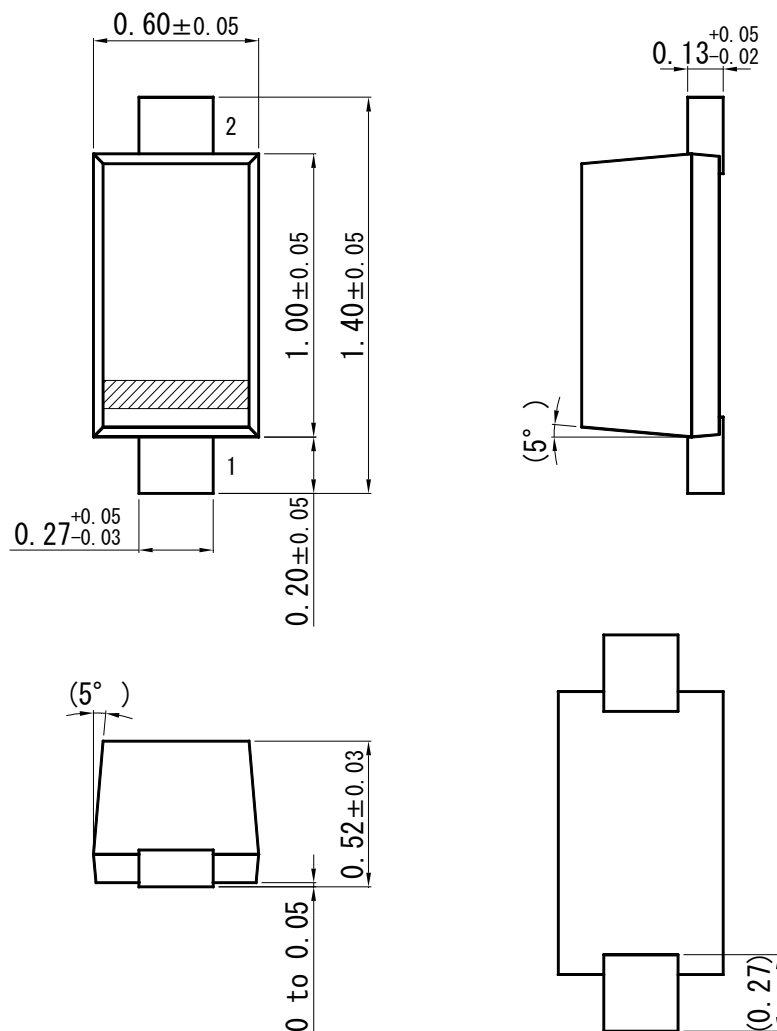


Technical Data ( reference )

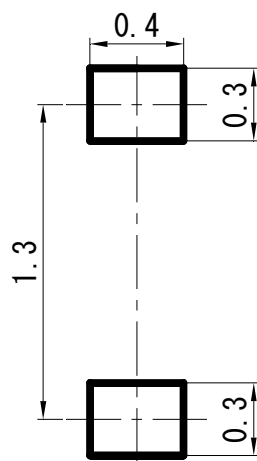


SSSMini2-F4-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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